

FIG. 1 (PRIOR ART)

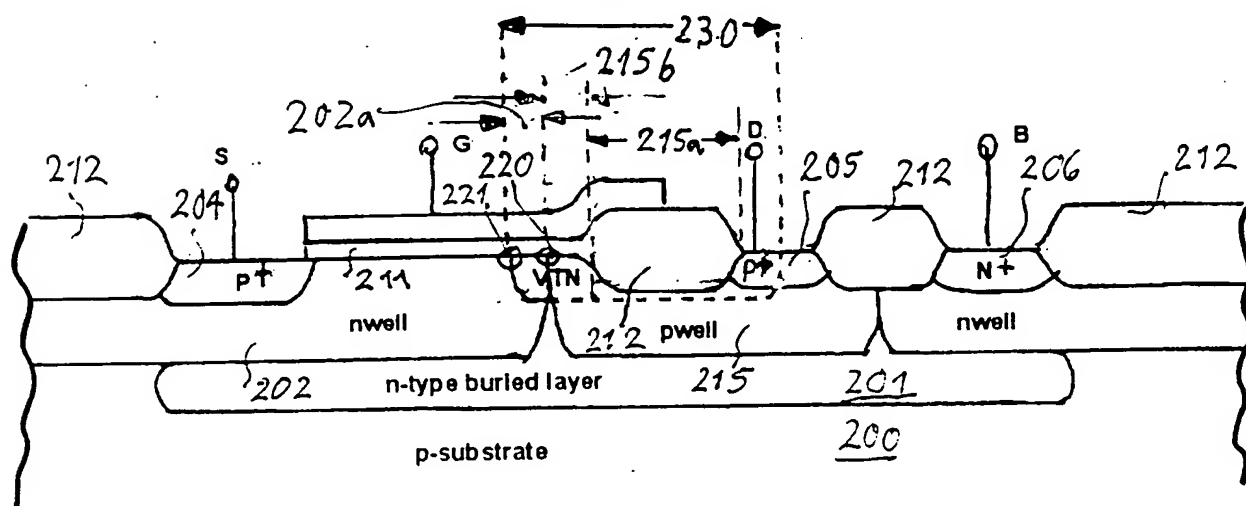
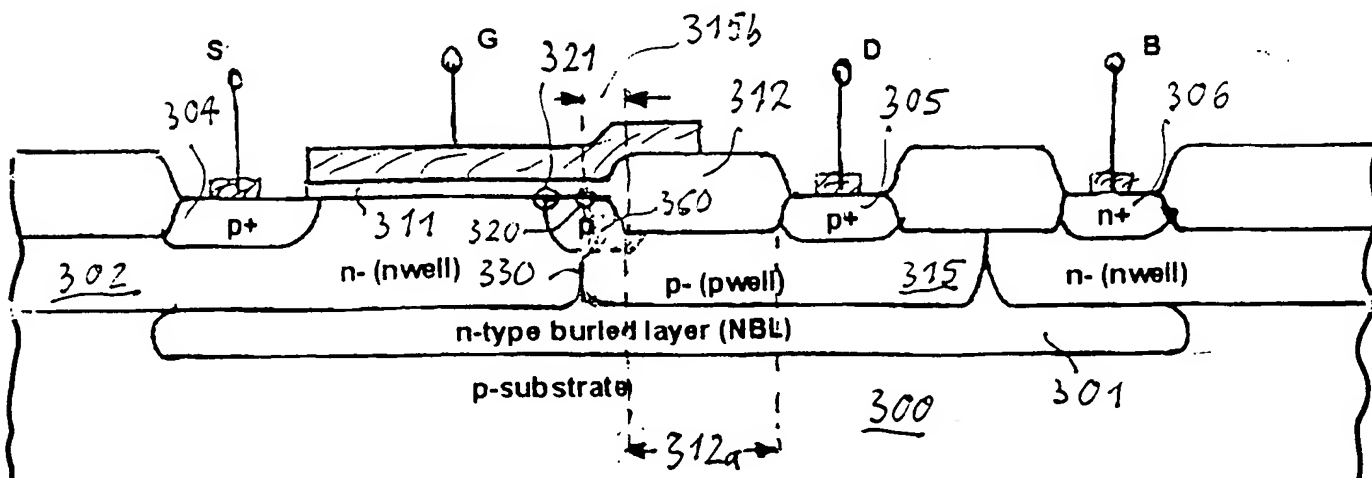


FIG. 2



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FILE 3

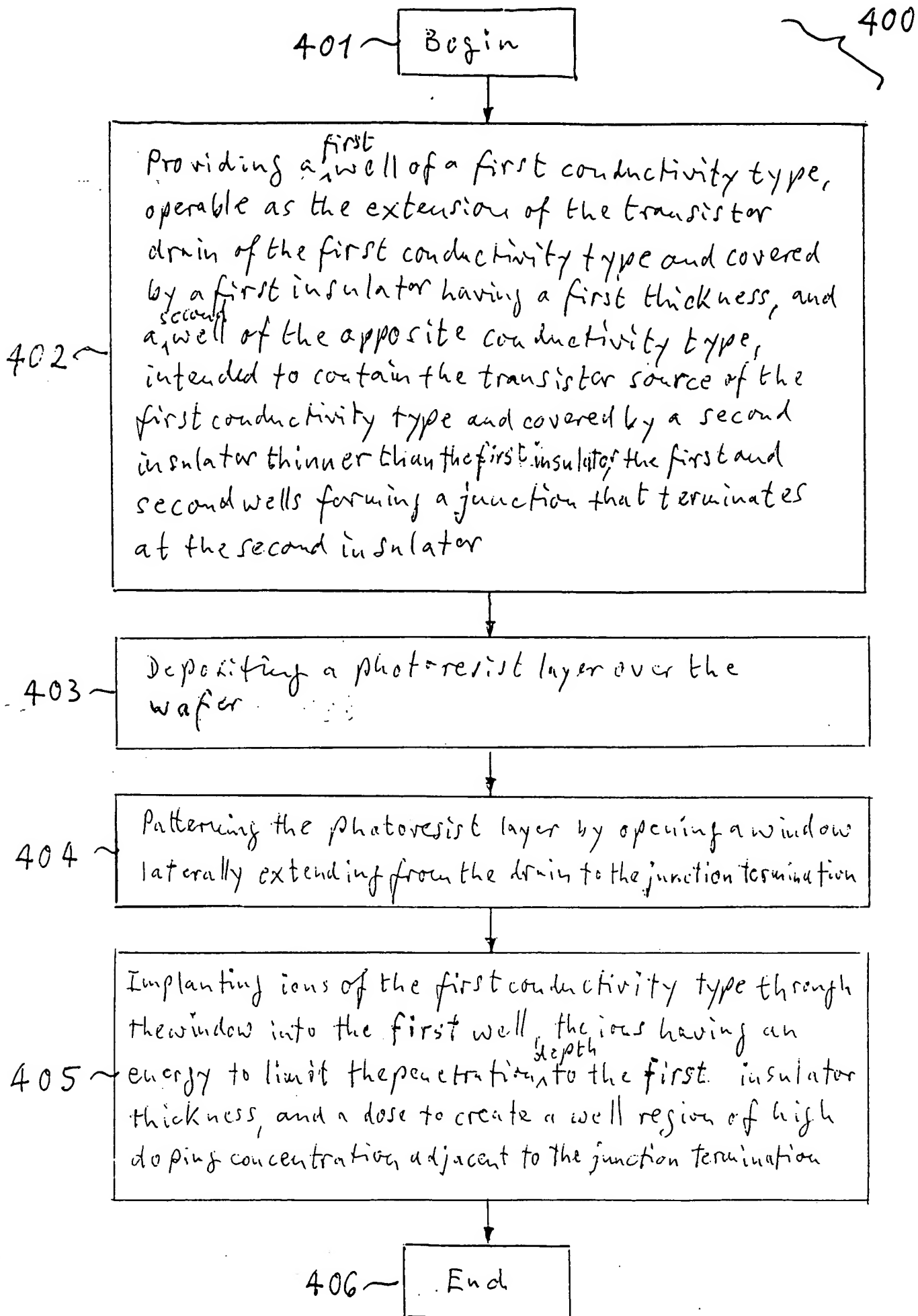


FIG. 4

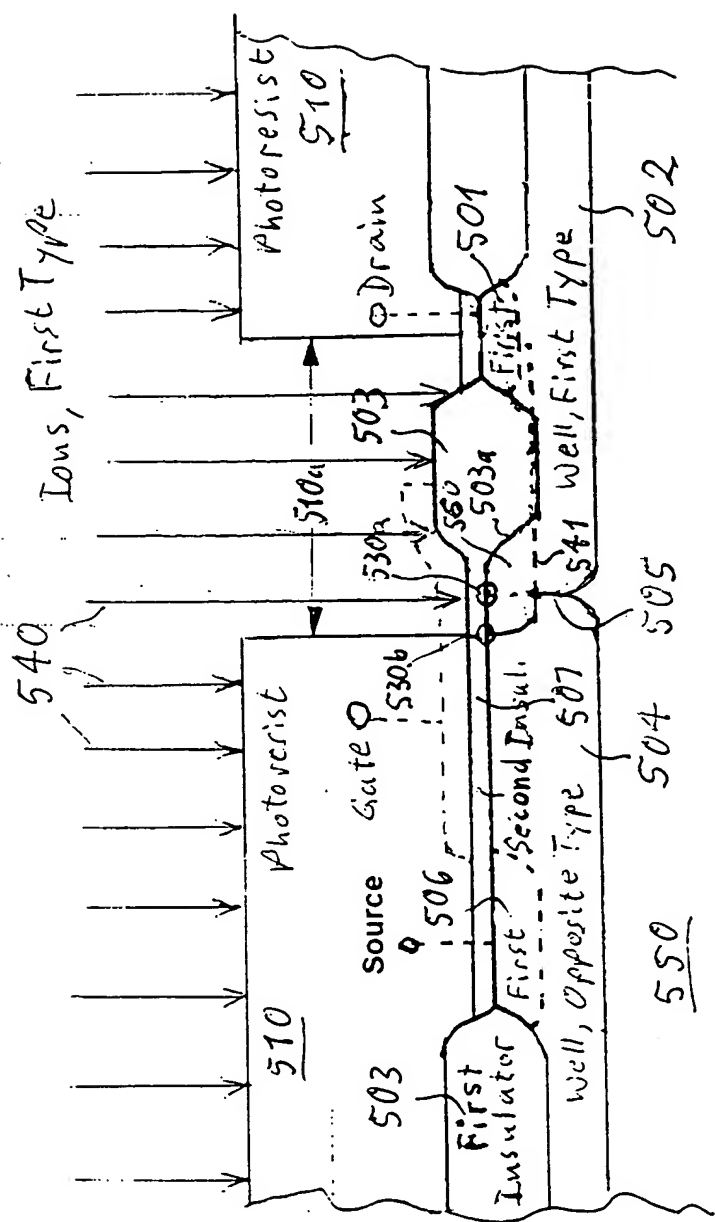


FIG. 5

600

601~ Begin

602~ Providing a semiconductor wafer of a first conductivity type

603~ Forming a buried layer of the opposite conductivity type

604~ Forming a first well of opposite conductivity type

605~ Forming a second well of the first conductivity type

606~ Forming a first (thick) insulator layer

607~ Forming a second (thin) insulator over active regions, protecting the junction ^{end point} between the first and second well

608~ Depositing photoresist layer

609~ Opening window in photoresist layer from drain region to junction end point

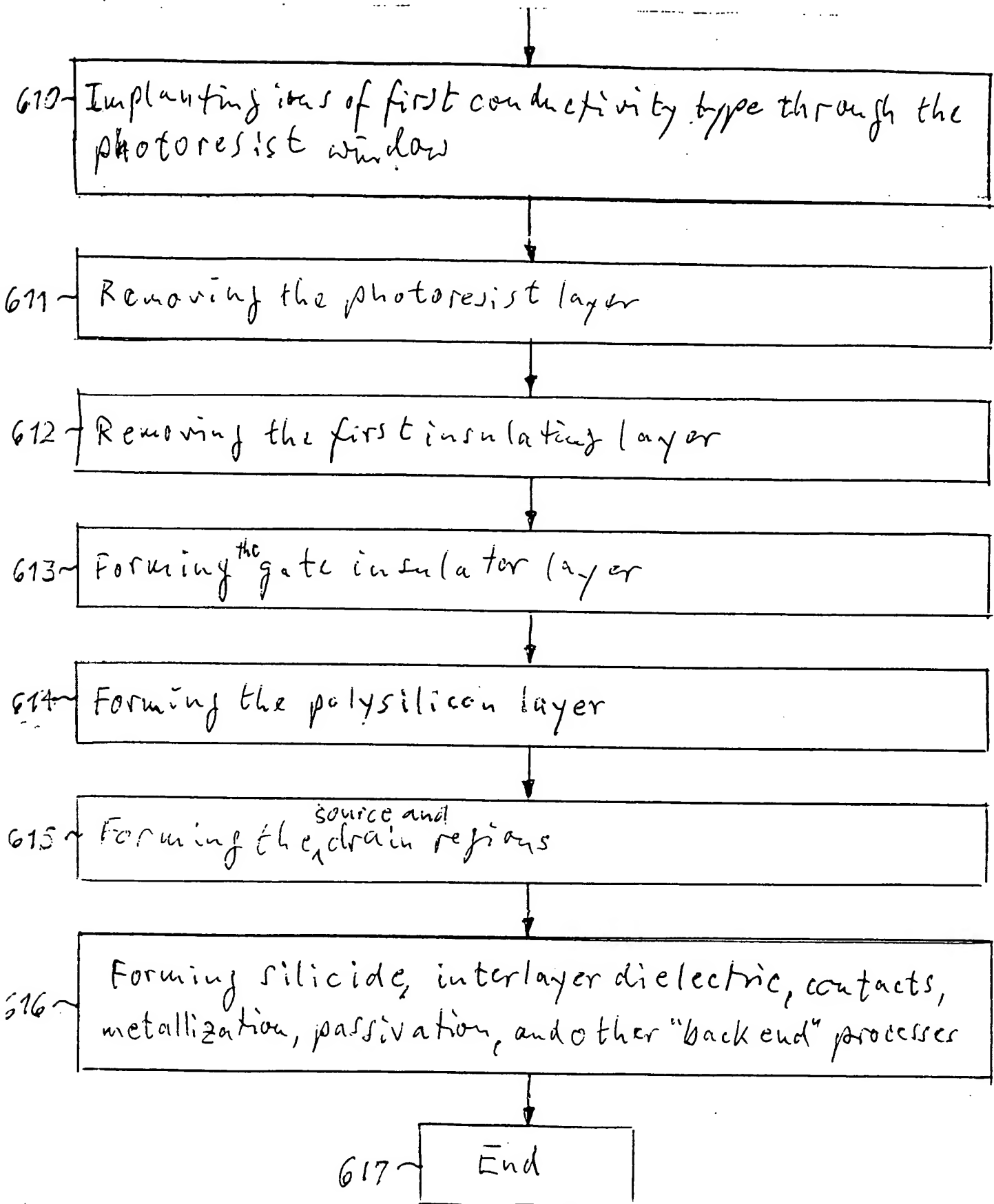


FIG. 6

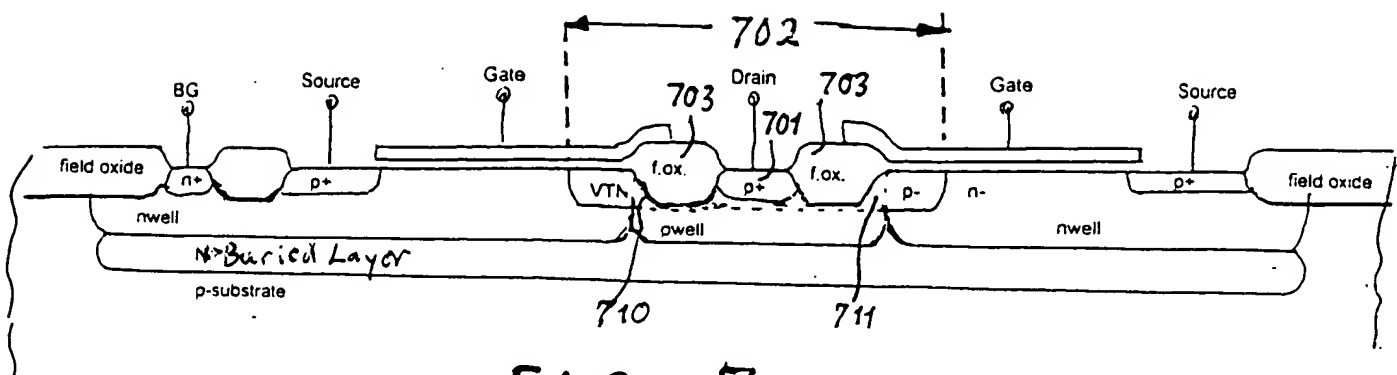


FIG. 7

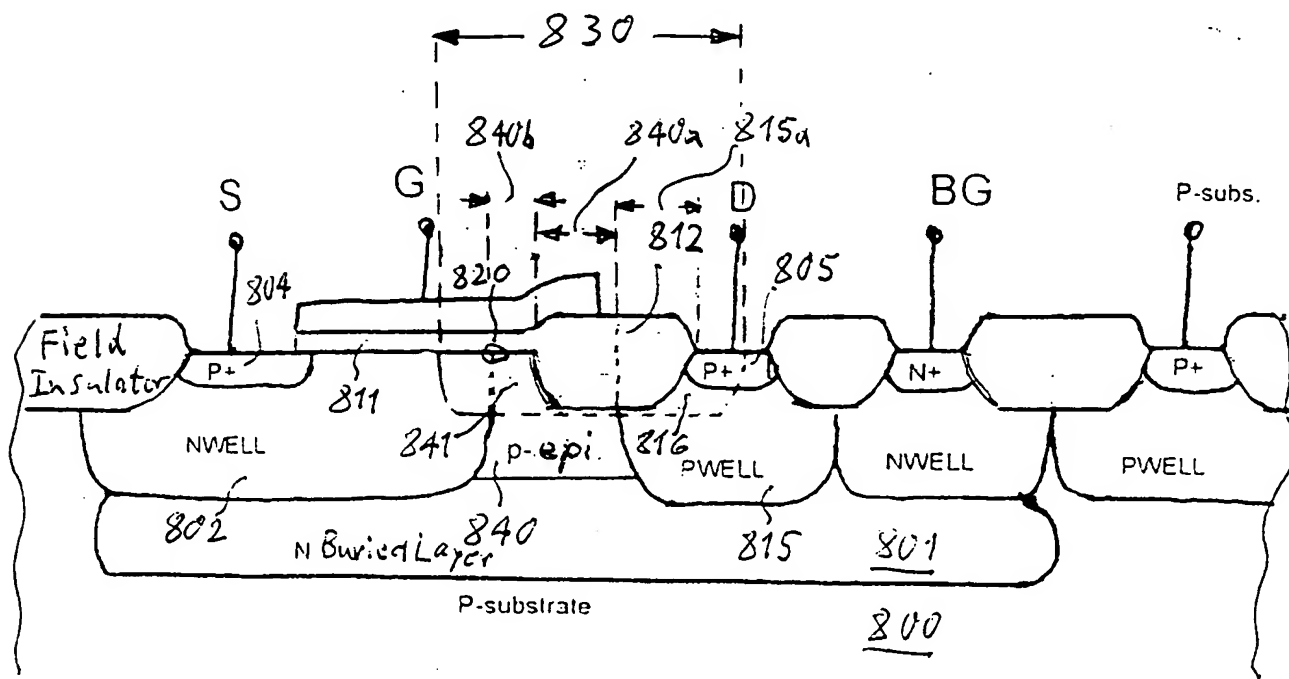


FIG. 8

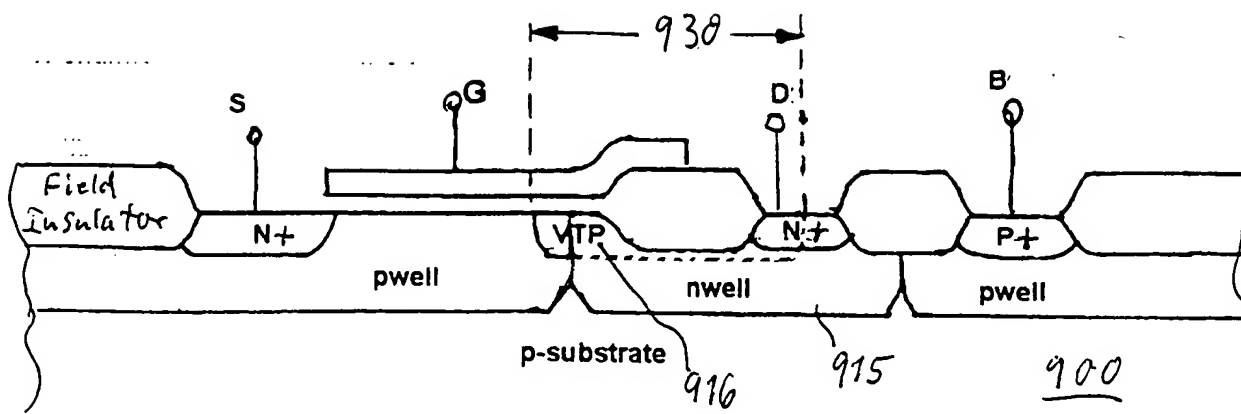


FIG. 9

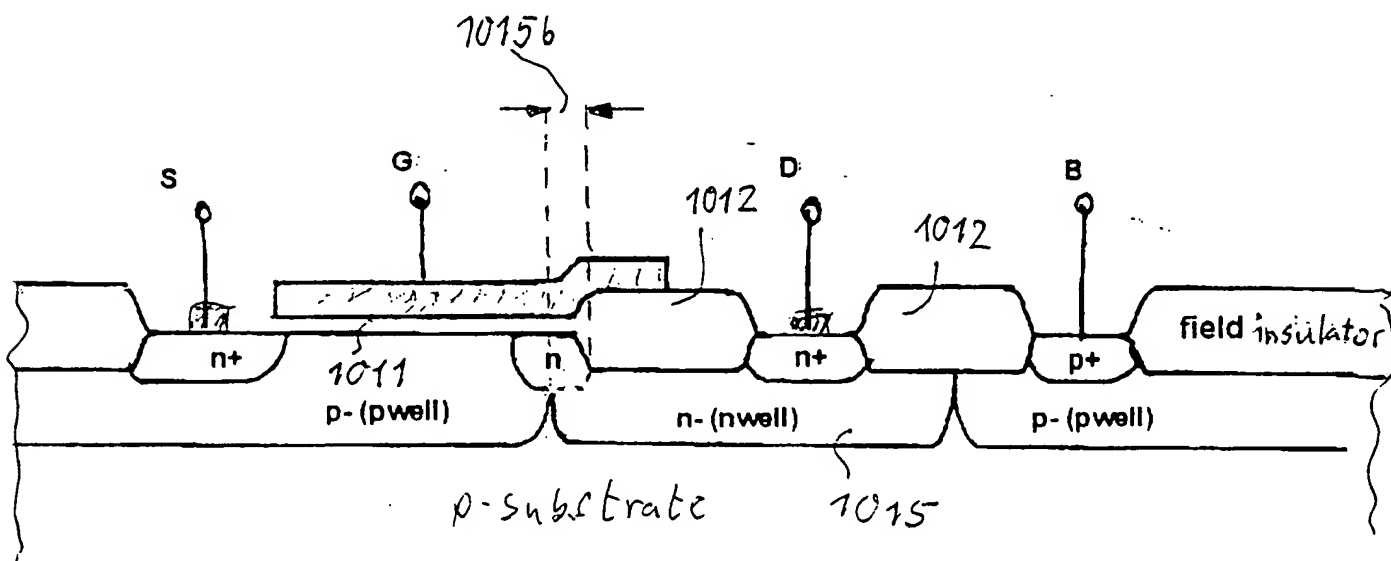


FIG. 10

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